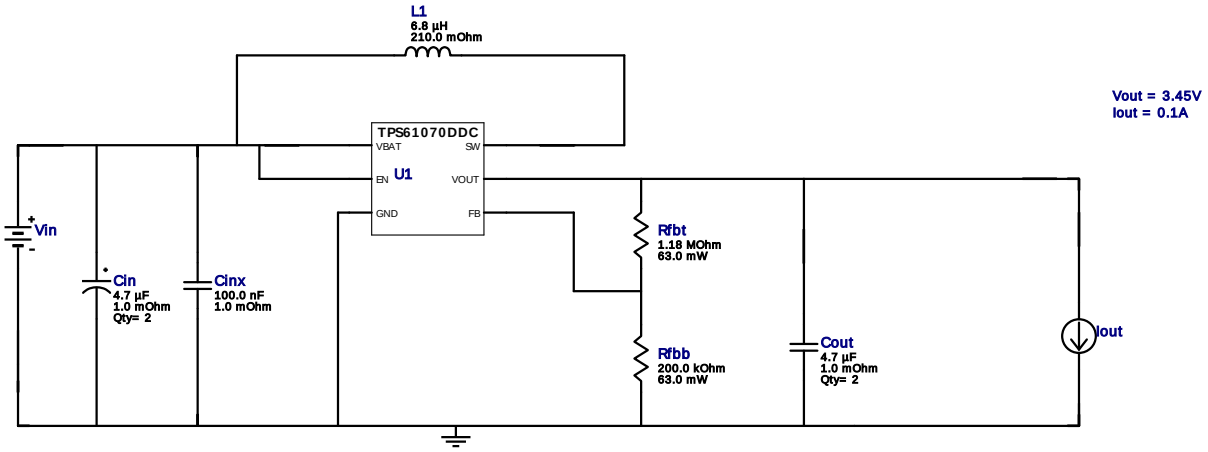
WEBENCH® Design Report

VinMin = 2.0V
VinMax = 3.1V
Vout = 3.45V
Iout = 0.1A

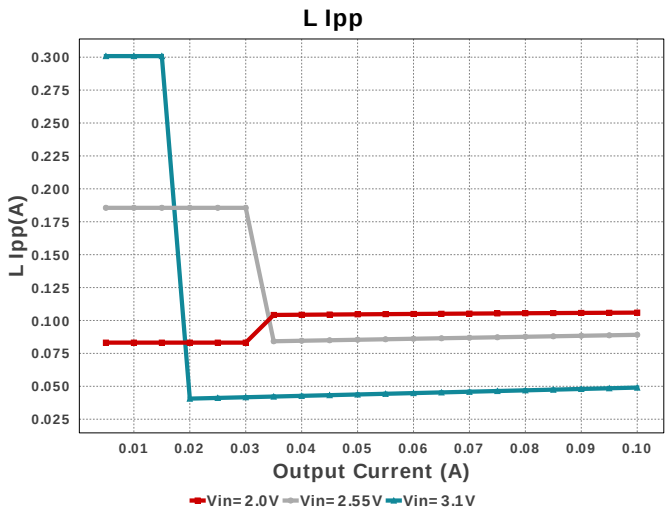
Device = TPS61070DDCR
Topology = Boost
Created = 2019-06-06 03:32:27.338
BOM Cost = NA
BOM Count = 9
Total Pd = 0.07W

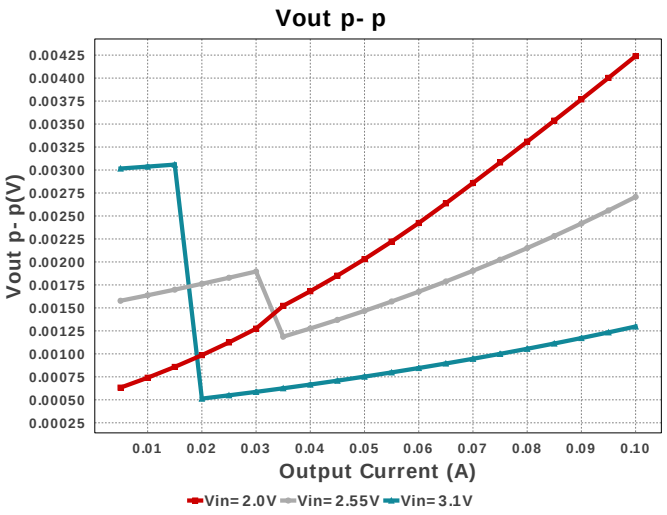
Design : 6569 TPS61070DDCR
TPS61070DDCR 2V-3.1V to 3.45V @ 0.1A

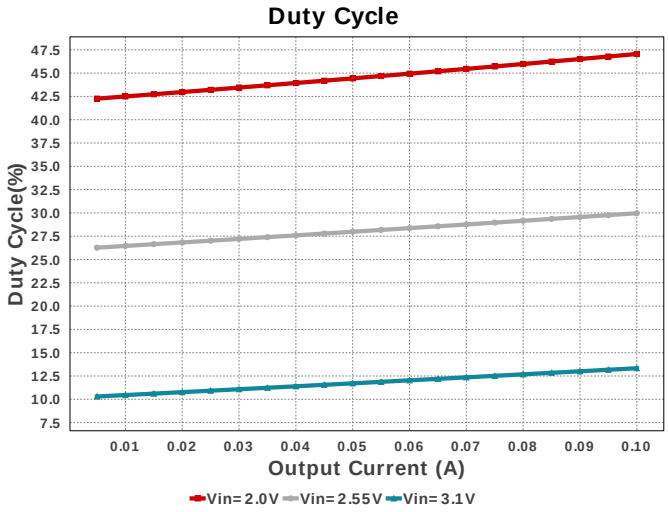


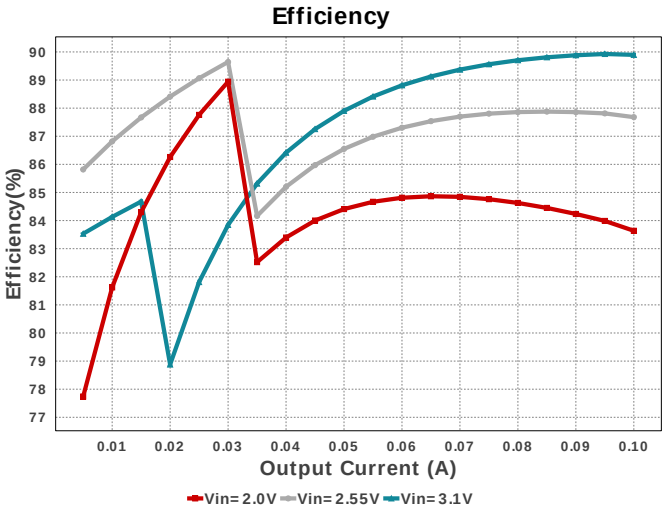
Electrical BOM

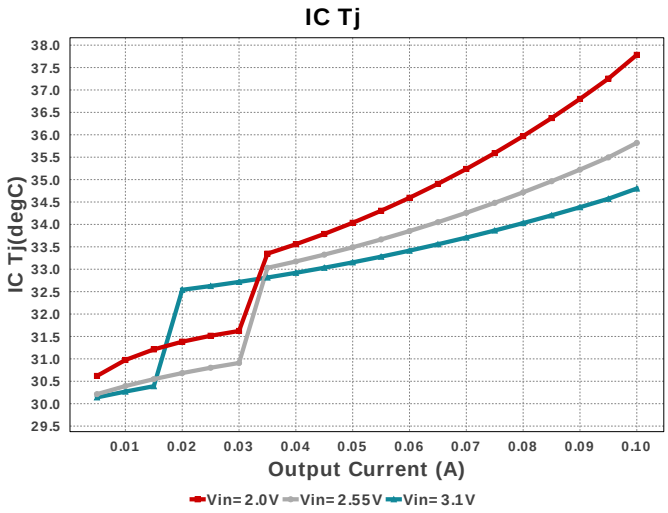
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cin	CUSTOM	CUSTOM Series= 593D	Cap= 4.7 uF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 870.0 mA	2	NA	7343-31 0 mm^2
Cinx	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cout	CUSTOM	CUSTOM Series= X7S	Cap= 4.7 uF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	2	NA	0805 0 mm^2
L1	CUSTOM	CUSTOM	L= 6.8 µH 210.0 mOhm	1	NA	CBC2518 0 mm^2
Rfbb	Vishay-Dale	CRCW0402200KFKED Series= CRCW..e3	Res= 200.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rfbt	Vishay-Dale	CRCW04021M18FKED Series= CRCW..e3	Res= 1.18 MOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
U1	Texas Instruments	TPS61070DDCR	Switcher	1	$0.45	DDC0006A_N 10 mm^2

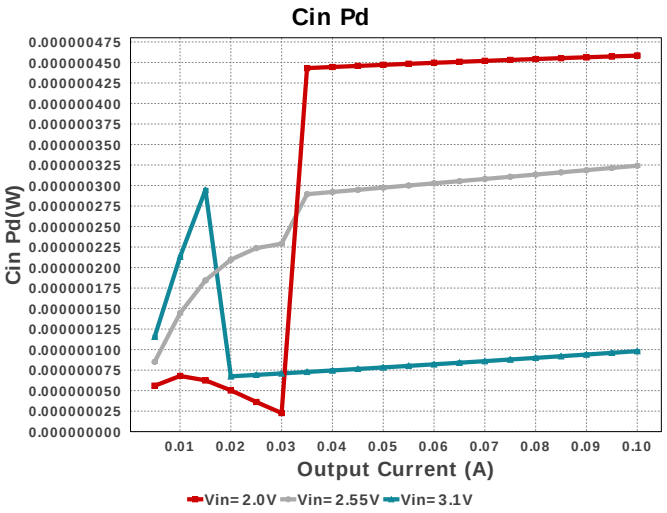


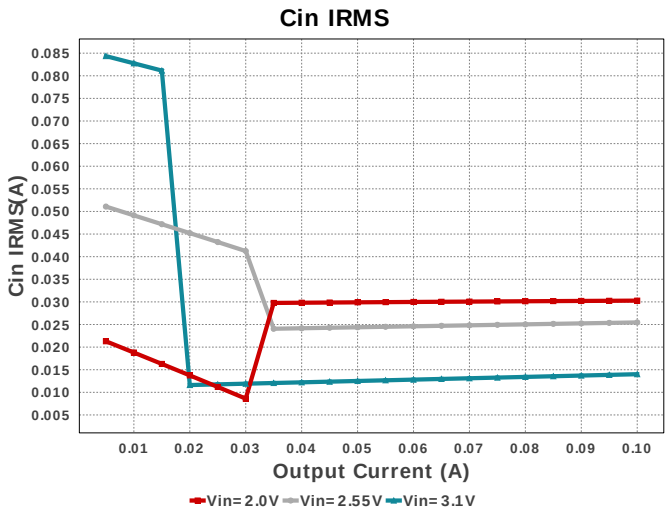


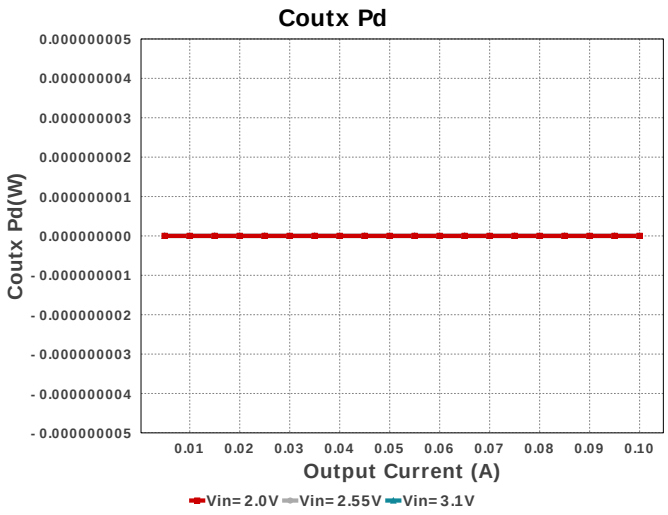


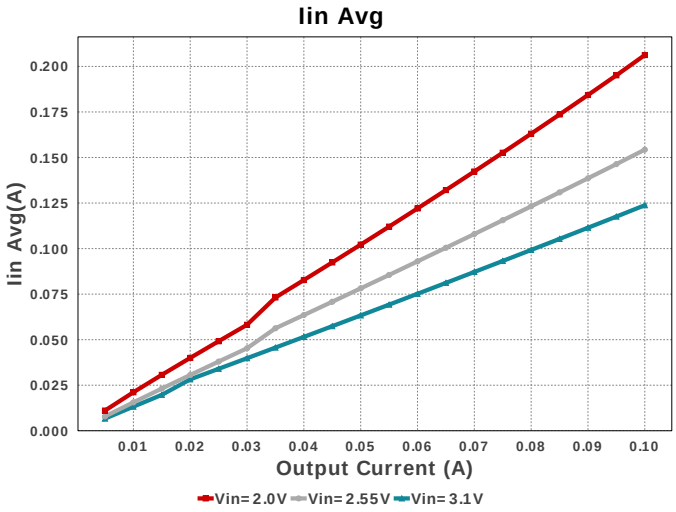


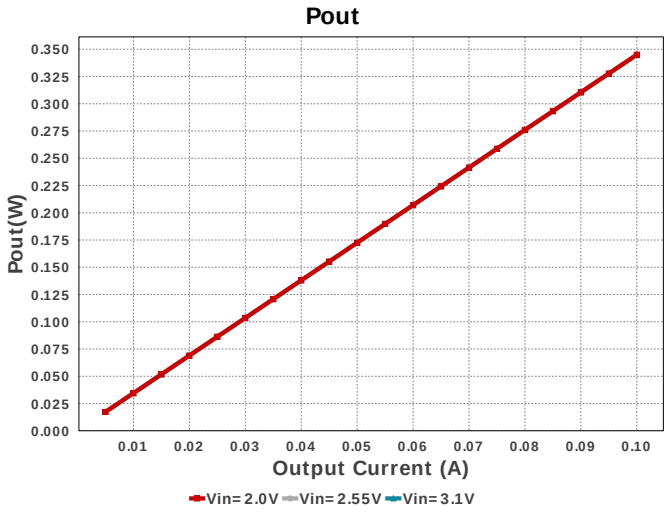


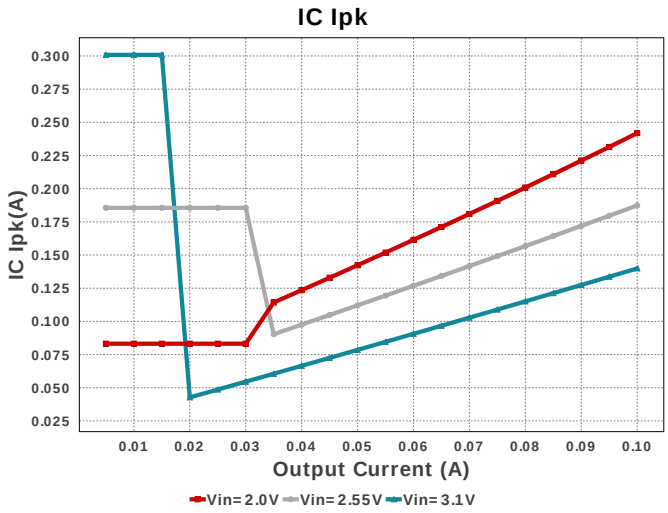


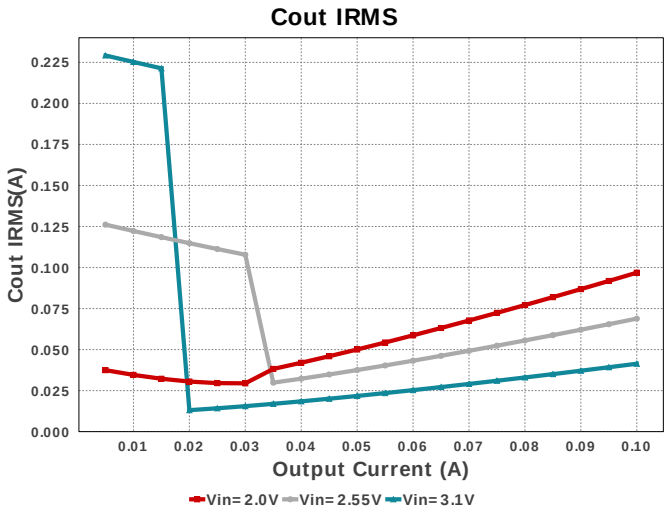


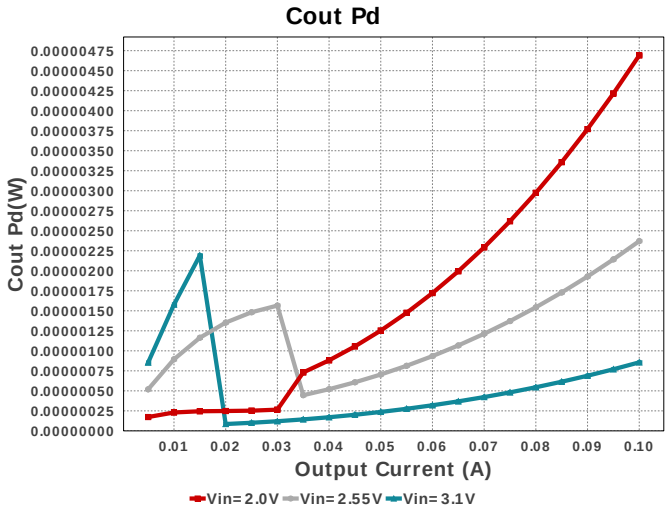


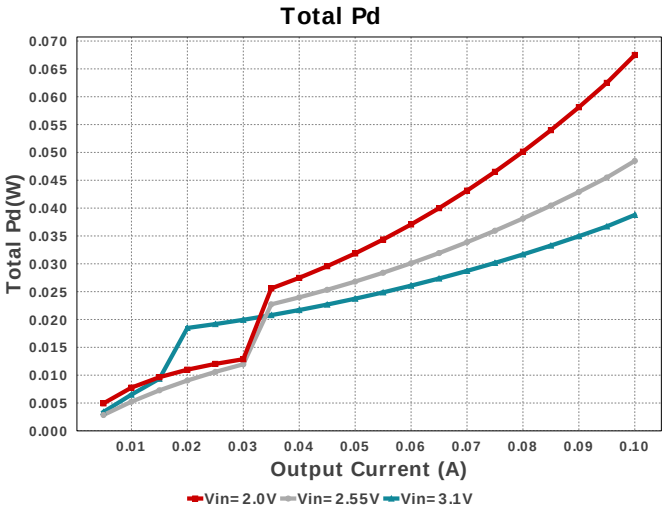


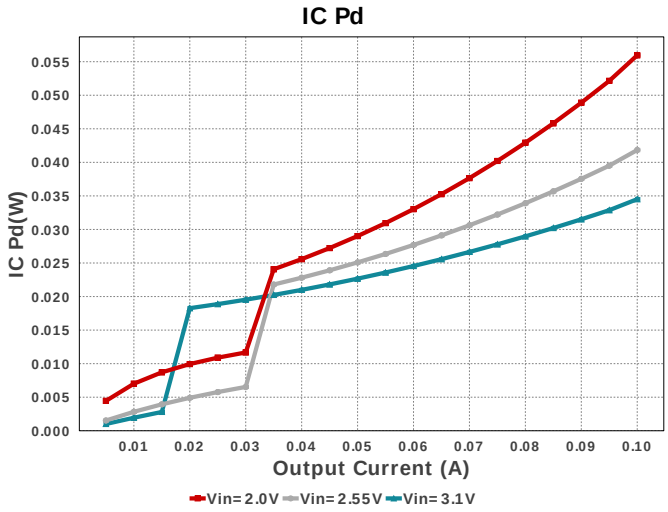


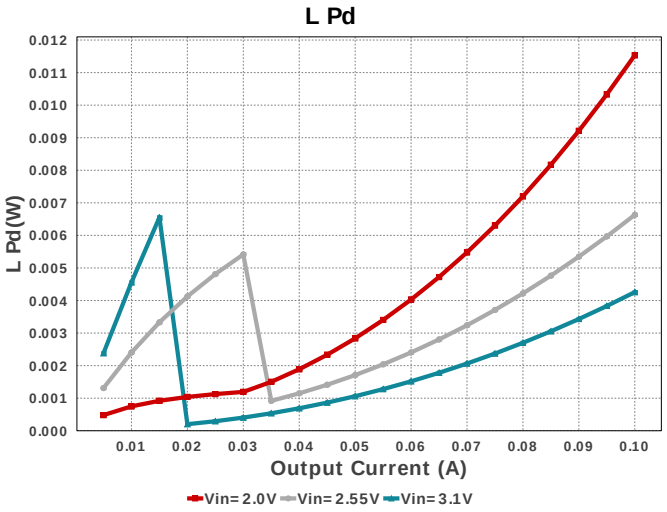


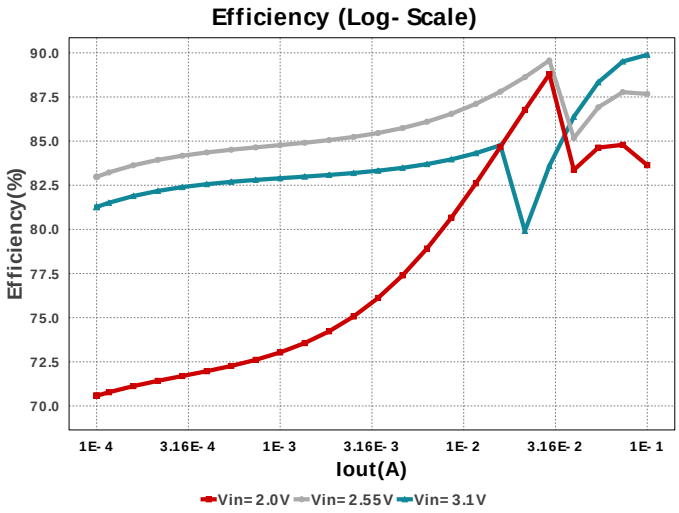












Operating Values

#	Name	Value	Category	Description
1.	BOM Count	9		Total Design BOM count
2.	Total BOM	NA		Total BOM Cost
3.	Cin IRMS	30.277 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	458.34 nW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	96.859 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	4.691 µW	Capacitor	Output capacitor power dissipation
7.	Coutx Pd	0.0 W	Capacitor	Output capacitor_x power loss
8.	IC Ipk	241.853 mA	IC	Peak switch current in IC
9.	IC Pd	55.589 mW	IC	IC power dissipation
10.	IC Tj	37.732 degC	IC	IC junction temperature
11.	ICThetaJA	139.1 degC/W	IC	IC junction-to-ambient thermal resistance

#	Name	Value	Category	Description
12.	Iin Avg	206.07 mA	IC	Average input current
13.	L Ipp	105.976 mA	Inductor	Peak-to-peak inductor ripple current
14.	L Pd	11.531 mW	Inductor	Inductor power dissipation
15.	Cin Pd	458.34 nW	Power	Input capacitor power dissipation
16.	Cout Pd	4.691 µW	Power	Output capacitor power dissipation
17.	Coutx Pd	0.0 W	Power	Output capacitor_x power loss
18.	IC Pd	55.589 mW	Power	IC power dissipation
19.	L Pd	11.531 mW	Power	Inductor power dissipation
20.	Total Pd	67.133 mW	Power	Total Power Dissipation
21.	Duty Cycle	47.052 %	System Information	Duty cycle
22.	Efficiency	83.711 %	System Information	Steady state efficiency
23.	FootPrint	160.0 mm^2	System Information	Total Foot Print Area of BOM components
24.	Frequency	1.2 MHz	System Information	Switching frequency
25.	Iout	100.0 mA	System Information	Iout operating point
26.	Mode	BOOST PWM CCM	System Information	PWM/PFM Mode
27.	Pout	345.0 mW	System Information	Total output power
28.	Vin	2.0 V	System Information	Vin operating point
29.	Vout Actual	3.45 V	System Information	Vout Actual calculated based on selected voltage divider resistors
30.	Vout Tolerance	8.136 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
31.	Vout p-p	4.239 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	100.0 m	Maximum Output Current
VinMax	3.1	Maximum input voltage
VinMin	2.0	Minimum input voltage
Vout	3.45	Output Voltage
base_pn	TPS61070	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

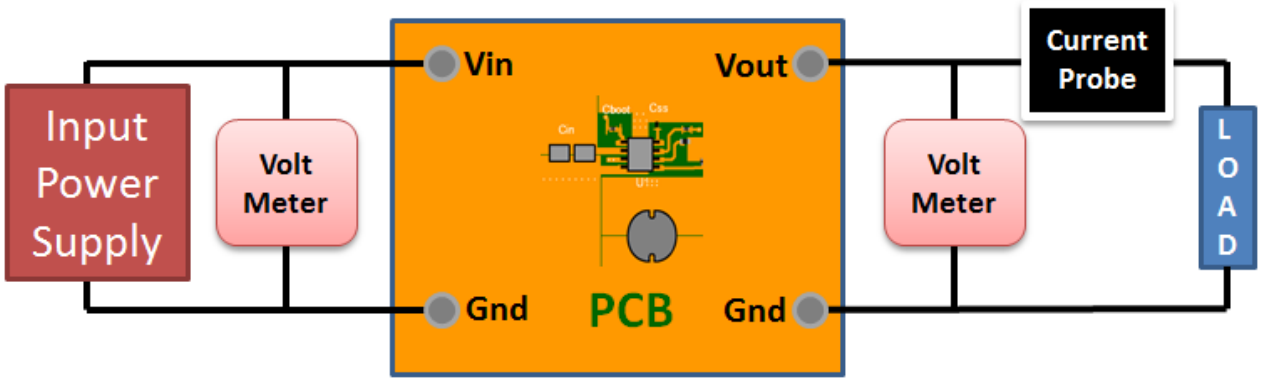
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 2.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

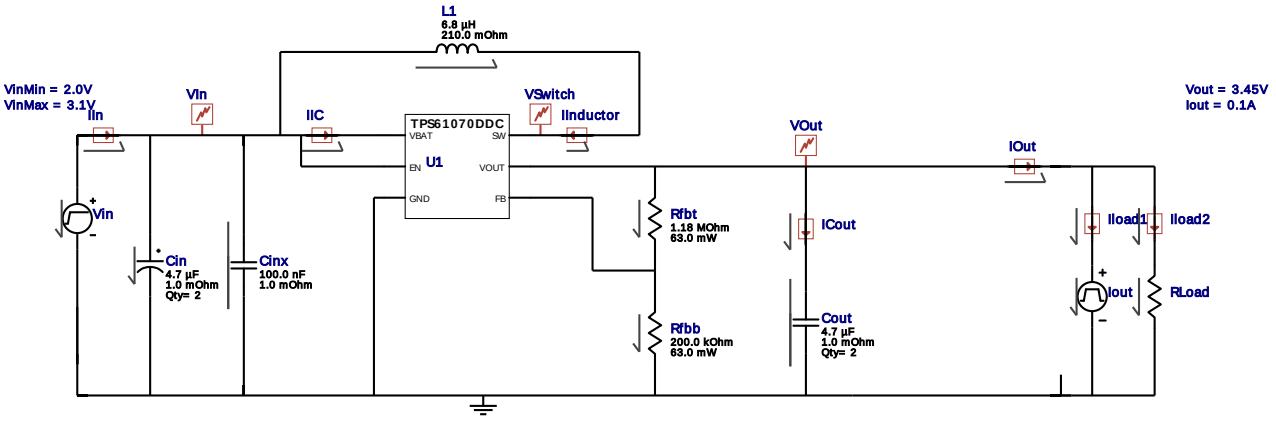


WEBENCH® Electrical Simulation Report

Design Id = 6569

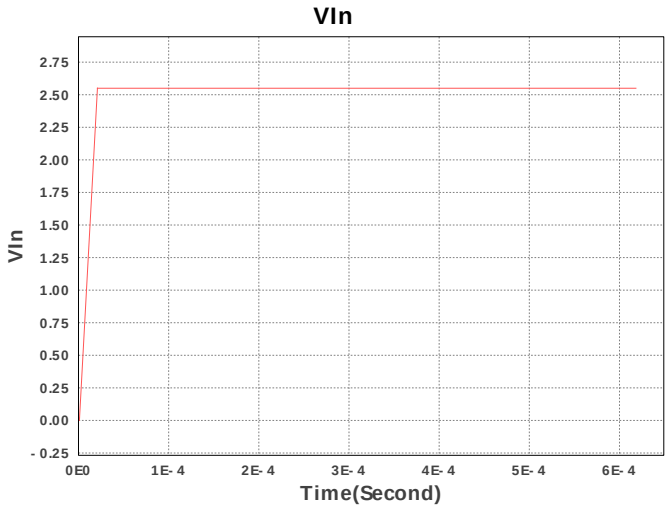
sim_id = 1

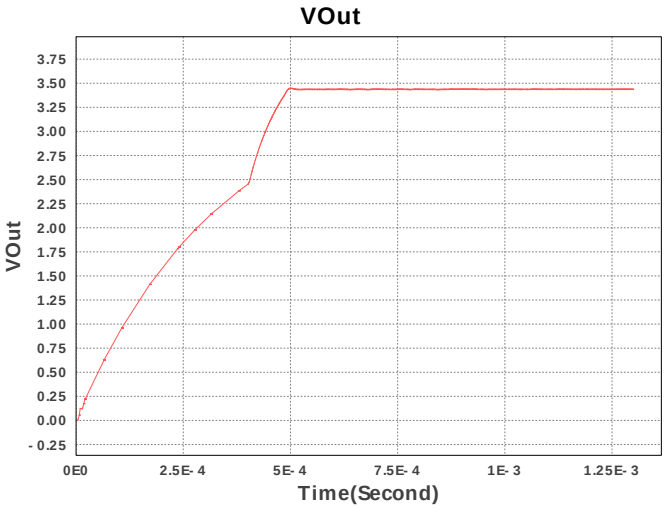
Simulation Type = 2-Step Startup



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cout	IC	Initial Voltage	0 V
2.	Iout	signal_type	Signal Type	PULSE
		I1	Initial Load Current	0 A
		I2	Full Load Current	0.0 A
		Td	Initial Time Delay	1m s
		Tr	Rise Time	10u s
3.	RLoad	R	Load Resistance	34.5 Ohm

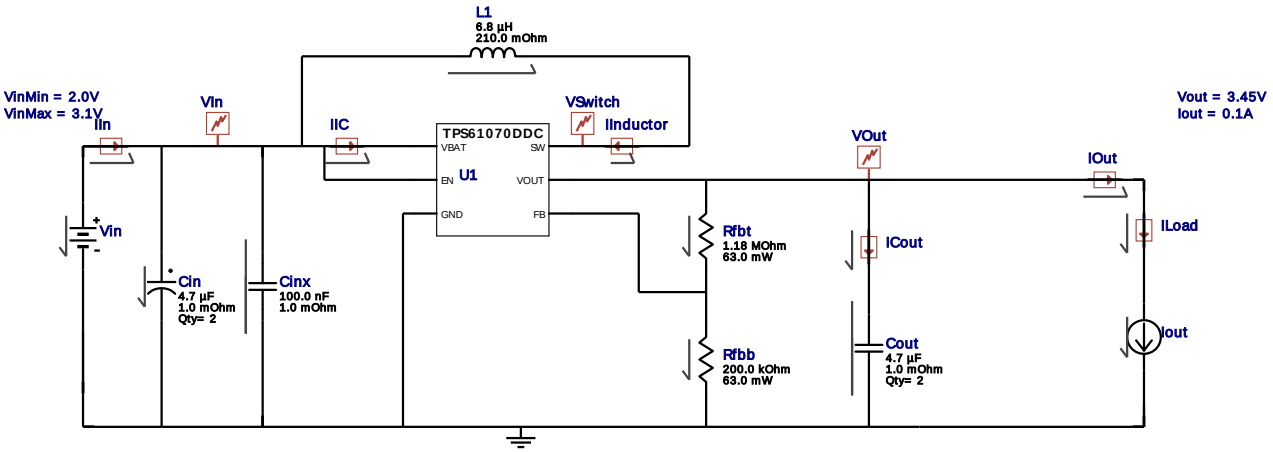




Design Id = 6569

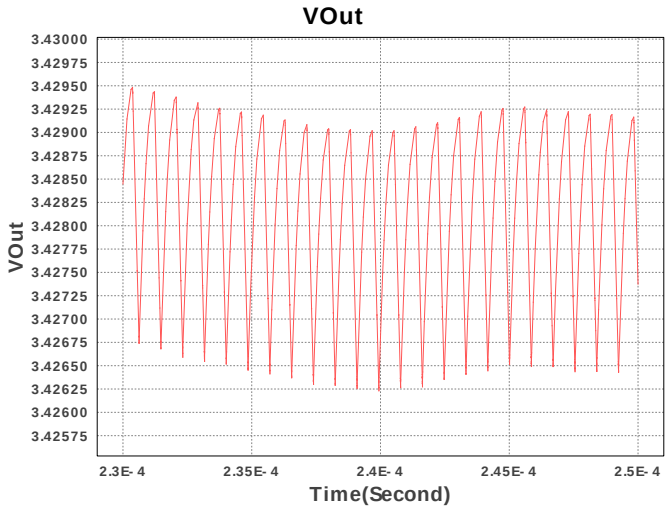
sim_id = 2

Simulation Type = Steady State



Simulation Parameters

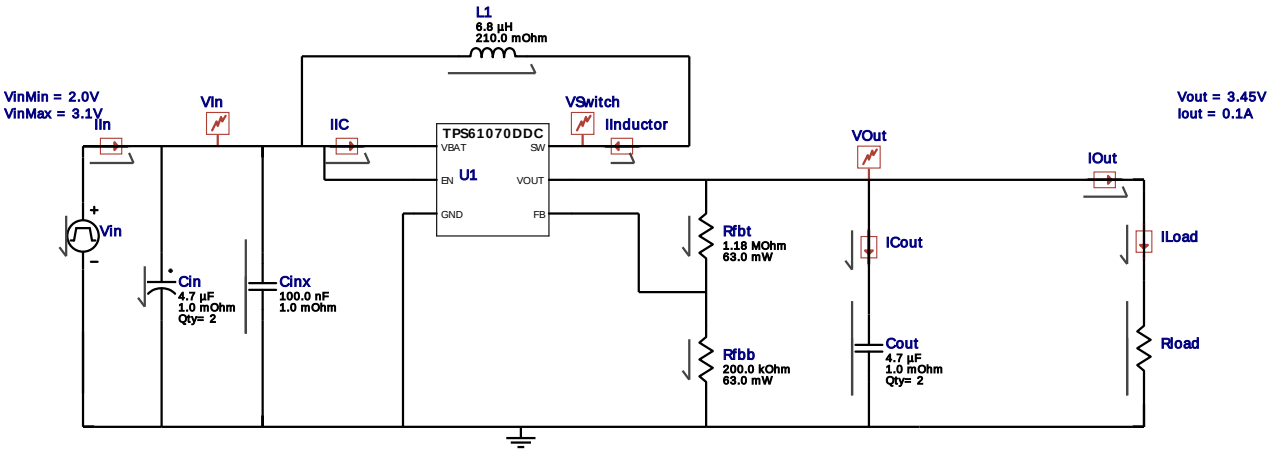
#	Name	Parameter Name	Description	Values
1.	Cout	IC	Initial Voltage	3.45 V
2.	L1	IC	Initial Current	0.1 A
3.	Iout	I	Load Current	0.1 A



Design Id = 6569

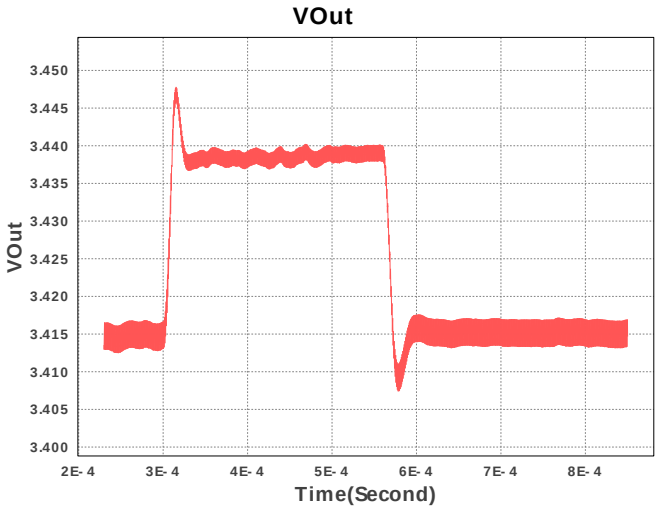
sim_id = 3

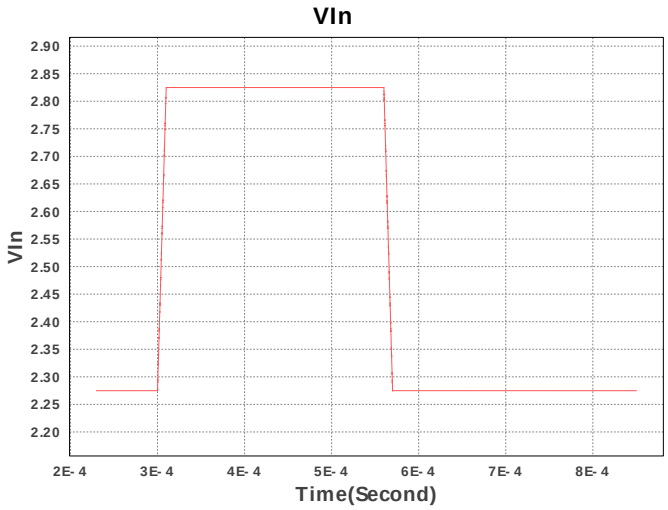
Simulation Type = Input Transient



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cout	IC	Initial Voltage	3.45 V
2.	L1	IC	Initial Current	0.1 A
3.	Rload	R	Load Resistance	34.5 Ohm

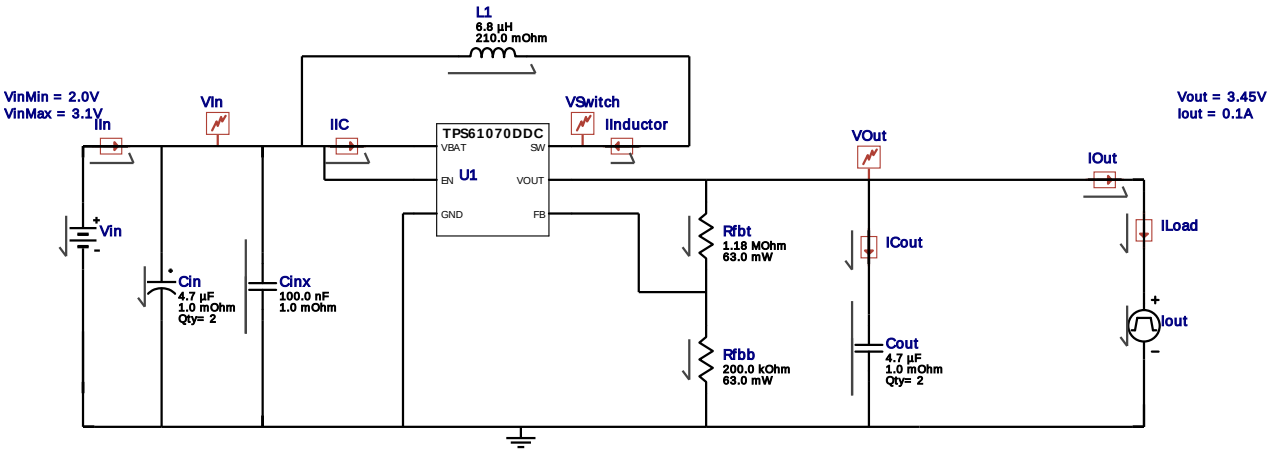




Design Id = 6569

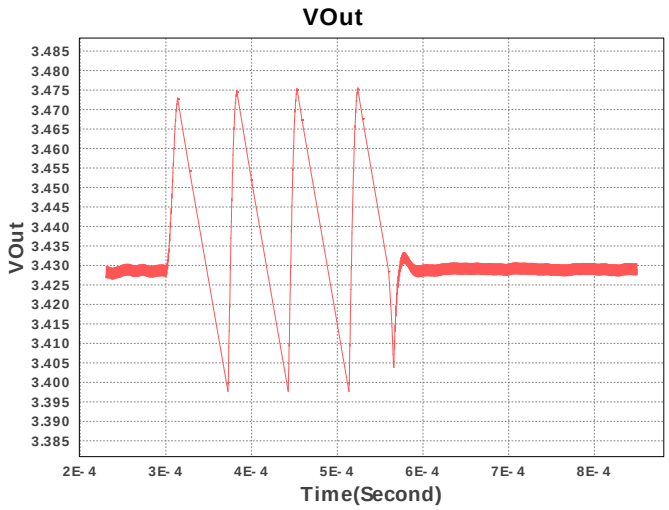
sim_id = 4

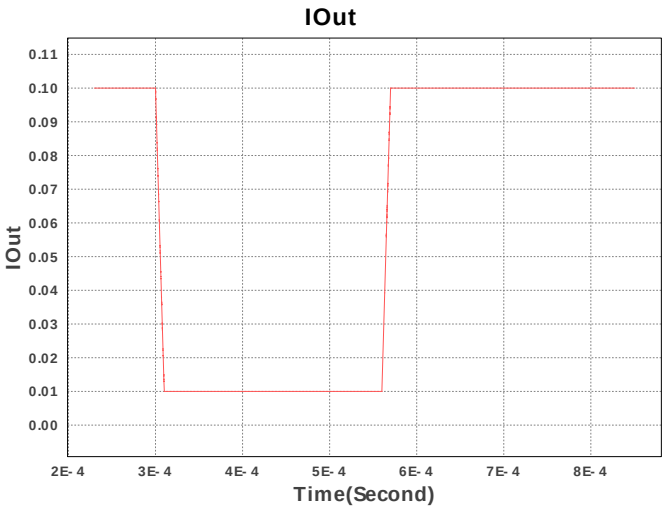
Simulation Type = Load Transient



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cout	IC	Initial Voltage	3.45 V
2.	L1	IC	Initial Current	0.1 A
3.	Iout	signal_type	Signal Type	PULSE
		I1	Initial Load Current	0.1 A
		I2	Minimum Load Current	0.01 A
		Td	Initial Time Delay	300u s
		Tf	Fall Time	10u s
		Tr	Rise Time	10u s
		Pw	Pulse Width	250u s





Design Assistance

1. Master key : B9C964572EBB957B[v1]
2. **TPS61070** Product Folder : http://www.ti.com/product/TPS61070 : contains the data sheet and other resources.